

ABSTRACT

A bonding sheet (1) according to the present invention includes a copper foil (2) and sinterable bonding films (3) formed on both faces of the copper foil (2). The bonding films (3) each contain copper particles and a solid reducing agent. The bonding sheet (1) is used to bond to a target object to be bonded (5) having at least one metal selected from gold, silver, copper, and nickel on a surface thereof. The present invention also provides a bonded structure (10) including; a bonded object (5) having at least one metal selected from gold, silver, copper, and nickel on a surface thereof; a copper foil (2); and a bonding layer (30) including a sintered structure of copper particles; and the bonded object (5) and the copper foil (2) are electrically connected to each other via the bonding layer (30).